

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Active
Core Processor	S08
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	48KB (48K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LQFP
Supplier Device Package	44-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc9s08aw48cfge

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



Chapter 3 Modes of Operation

3.1 Introduction

The operating modes of the MC9S08AW60 Series are described in this chapter. Entry into each mode, exit from each mode, and functionality while in each of the modes are described.

3.2 Features

- Active background mode for code development
- Wait mode:
 - CPU shuts down to conserve power
 - System clocks running
 - Full voltage regulation maintained
- Stop modes:
 - System clocks stopped; voltage regulator in standby
 - Stop2 Partial power down of internal circuits, RAM contents retained
 - Stop3 All internal circuits powered for fast recovery

3.3 Run Mode

This is the normal operating mode for the MC9S08AW60 Series. This mode is selected when the BKGD/MS pin is high at the rising edge of reset. In this mode, the CPU executes code from internal memory with execution beginning at the address fetched from memory at \$FFFE:\$FFFF after reset.

3.4 Active Background Mode

The active background mode functions are managed through the background debug controller (BDC) in the HCS08 core. The BDC, together with the on-chip debug module (DBG), provide the means for analyzing MCU operation during software development.

Active background mode is entered in any of five ways:

- When the BKGD/MS pin is low at the rising edge of reset
- When a BACKGROUND command is received through the BKGD pin
- When a BGND instruction is executed
- When encountering a BDC breakpoint
- When encountering a DBG breakpoint



the MCU secure. During development, whenever the FLASH is erased, it is good practice to immediately program the SEC00 bit to 0 in NVOPT so SEC01:SEC00 = 1:0. This would allow the MCU to remain unsecured after a subsequent reset.

The on-chip debug module cannot be enabled while the MCU is secure. The separate background debug controller can still be used for background memory access commands, but the MCU cannot enter active background mode except by holding BKGD/MS low at the rising edge of reset.

A user can choose to allow or disallow a security unlocking mechanism through an 8-byte backdoor security key. If the nonvolatile KEYEN bit in NVOPT/FOPT is 0, the backdoor key is disabled and there is no way to disengage security without completely erasing all FLASH locations. If KEYEN is 1, a secure user program can temporarily disengage security by:

- 1. Writing 1 to KEYACC in the FCNFG register. This makes the FLASH module interpret writes to the backdoor comparison key locations (NVBACKKEY through NVBACKKEY+7) as values to be compared against the key rather than as the first step in a FLASH program or erase command.
- 2. Writing the user-entered key values to the NVBACKKEY through NVBACKKEY+7 locations. These writes must be done in order starting with the value for NVBACKKEY and ending with NVBACKKEY+7. STHX should not be used for these writes because these writes cannot be done on adjacent bus cycles. User software normally would get the key codes from outside the MCU system through a communication interface such as a serial I/O.
- 3. Writing 0 to KEYACC in the FCNFG register. If the 8-byte key that was just written matches the key stored in the FLASH locations, SEC01:SEC00 are automatically changed to 1:0 and security will be disengaged until the next reset.

The security key can be written only from secure memory (either RAM or FLASH), so it cannot be entered through background commands without the cooperation of a secure user program.

The backdoor comparison key (NVBACKKEY through NVBACKKEY+7) is located in FLASH memory locations in the nonvolatile register space so users can program these locations exactly as they would program any other FLASH memory location. The nonvolatile registers are in the same 512-byte block of FLASH as the reset and interrupt vectors, so block protecting that space also block protects the backdoor comparison key. Block protects cannot be changed from user application programs, so if the vector space is block protected, the backdoor security key mechanism cannot permanently change the block protect, security settings, or the backdoor key.

Security can always be disengaged through the background debug interface by taking these steps:

- 1. Disable any block protections by writing FPROT. FPROT can be written only with background debug commands, not from application software.
- 2. Mass erase FLASH if necessary.
- 3. Blank check FLASH. Provided FLASH is completely erased, security is disengaged until the next reset.

To avoid returning to secure mode after the next reset, program NVOPT so SEC01:SEC00 = 1:0.



I bit in the CCR is 0 to allow interrupts. The global interrupt mask (I bit) in the CCR is initially set after reset which masks (prevents) all maskable interrupt sources. The user program initializes the stack pointer and performs other system setup before clearing the I bit to allow the CPU to respond to interrupts.

When the CPU receives a qualified interrupt request, it completes the current instruction before responding to the interrupt. The interrupt sequence obeys the same cycle-by-cycle sequence as the SWI instruction and consists of:

- Saving the CPU registers on the stack
- Setting the I bit in the CCR to mask further interrupts
- Fetching the interrupt vector for the highest-priority interrupt that is currently pending
- Filling the instruction queue with the first three bytes of program information starting from the address fetched from the interrupt vector locations

While the CPU is responding to the interrupt, the I bit is automatically set to avoid the possibility of another interrupt interrupting the ISR itself (this is called nesting of interrupts). Normally, the I bit is restored to 0 when the CCR is restored from the value stacked on entry to the ISR. In rare cases, the I bit may be cleared inside an ISR (after clearing the status flag that generated the interrupt) so that other interrupts can be serviced without waiting for the first service routine to finish. This practice is not recommended for anyone other than the most experienced programmers because it can lead to subtle program errors that are difficult to debug.

The interrupt service routine ends with a return-from-interrupt (RTI) instruction which restores the CCR, A, X, and PC registers to their pre-interrupt values by reading the previously saved information off the stack.

NOTE

For compatibility with the M68HC08, the H register is not automatically saved and restored. It is good programming practice to push H onto the stack at the start of the interrupt service routine (ISR) and restore it immediately before the RTI that is used to return from the ISR.

When two or more interrupts are pending when the I bit is cleared, the highest priority source is serviced first (see Table 5-1).

5.5.1 Interrupt Stack Frame

Figure 5-1 shows the contents and organization of a stack frame. Before the interrupt, the stack pointer (SP) points at the next available byte location on the stack. The current values of CPU registers are stored on the stack starting with the low-order byte of the program counter (PCL) and ending with the CCR. After stacking, the SP points at the next available location on the stack which is the address that is one less than the address where the CCR was saved. The PC value that is stacked is the address of the instruction in the main program that would have executed next if the interrupt had not occurred.



Chapter 6 Parallel Input/Output

- Software-controlled slew rate output buffers
- Eight port A pins
- Eight port B pins shared with ADC1
- Seven port C pins shared with SCI2, IIC1, and MCLK
- Eight port D pins shared with ADC1, KBI1, and TPM1 and TPM2 external clock inputs
- Eight port E pins shared with SCI1, TPM1, and SPI1
- Eight port F pins shared with TPM1 and TPM2
- Seven port G pins shared with XTAL, EXTAL, and KBI1

6.3 Pin Descriptions

The MC9S08AW60 Series has a total of 54 parallel I/O pins in seven ports (PTA–PTG). Not all pins are bonded out in all packages. Consult the pin assignment in Chapter 2, "Pins and Connections," for available parallel I/O pins. All of these pins are available for general-purpose I/O when they are not used by other on-chip peripheral systems.

After reset, the shared peripheral functions are disabled so that the pins are controlled by the parallel I/O. All of the parallel I/O are configured as inputs (PTxDDn = 0). The pin control functions for each pin are configured as follows: slew rate control enabled (PTxSEn = 1), low drive strength selected (PTxDSn = 0), and internal pullups disabled (PTxPEn = 0).

The following paragraphs discuss each port and the software controls that determine each pin's use.

6.3.1 Port A

			Figure	e 6-1. Port	A Pin Na	imes			
	MCU Pin:	PTA7	PTA6	PTA5	PTA4	PTA3	PTA2	PTA1	PTA0
Port A		Bit 7	6	5	4	3	2	1	Bit 0

Port A pins are general-purpose I/O pins. Parallel I/O function is controlled by the port A data (PTAD) and data direction (PTADD) registers which are located in page zero register space. The pin control registers, pullup enable (PTAPE), slew rate control (PTASE), and drive strength select (PTADS) are located in the high page registers. Refer to Section 6.4, "Parallel I/O Control" for more information about general-purpose I/O control and Section 6.5, "Pin Control" for more information about pin control.

6.3.2 Port B

Port B		Bit 7	6	5	4	3	2	1	Bit 0
	MCU Pin:	PTB7/ AD1P7	PTB6/ AD1P6	PTB5/ AD1P5	PTB4/ AD1P4	PTB3/ AD1P3	PTB2/ AD1P2	PTB1/ AD1P1	PTB0/ AD1P0

Figure 6-2. Port B Pin Names

MC9S08AW60 Data Sheet, Rev 2



Chapter 6 Parallel Input/Output

pullup enable (PTDPE), slew rate control (PTDSE), and drive strength select (PTDDS) are located in the high page registers. Refer to Section 6.4, "Parallel I/O Control" for more information about general-purpose I/O control and Section 6.5, "Pin Control" for more information about pin control.

Port D general-purpose I/O are shared with the ADC, KBI, and TPM1 and TPM2 external clock inputs. When any of these shared functions is enabled, the direction, input or output, is controlled by the shared function and not by the data direction register of the parallel I/O port. When a pin is shared with both the ADC and a digital peripheral function, the ADC has higher priority. For example, in the case that both the ADC and the KBI are configured to use PTD7 then the pin is controlled by the ADC module.

Refer to Chapter 10, "Timer/PWM (S08TPMV2)" for more information about using port D pins as TPM external clock inputs.

Refer to Chapter 14, "Analog-to-Digital Converter (S08ADC10V1)" for more information about using port D pins as analog inputs.

Refer to Chapter 9, "Keyboard Interrupt (S08KBIV1)" for more information about using port D pins as keyboard inputs.

6.3.5 Port E

Port E

	Bit 7	6	5	4	3	2	1	Bit 0
MCU Pin:	PTE7/	PTE6/	PTE5/	PTE4/	PTE3/	PTE2/	PTE1/	PTE0/
	SPSCK1	MOSI1	MISO1	SS1	TPM1CH1	TPM1CH0	RxD1	TxD1

Figure 6-5. Port E Pin Names

Port E pins are general-purpose I/O pins. Parallel I/O function is controlled by the port E data (PTED) and data direction (PTEDD) registers which are located in page zero register space. The pin control registers, pullup enable (PTEPE), slew rate control (PTESE), and drive strength select (PTEDS) are located in the high page registers. Refer to Section 6.4, "Parallel I/O Control" for more information about general-purpose I/O control and Section 6.5, "Pin Control" for more information about pin control.

Port E general-purpose I/O is shared with SCI1, SPI, and TPM1 timer channels. When any of these shared functions is enabled, the direction, input or output, is controlled by the shared function and not by the data direction register of the parallel I/O port. Also, for pins which are configured as outputs by the shared function, the output data is controlled by the shared function and not by the port data register.

Refer to Chapter 11, "Serial Communications Interface (S08SCIV2)" for more information about using port E pins as SCI pins.

Refer to Chapter 12, "Serial Peripheral Interface (S08SPIV3)" for more information about using port E pins as SPI pins.

Refer to Chapter 10, "Timer/PWM (S08TPMV2)" for more information about using port E pins as TPM channel pins.



Chapter 6 Parallel Input/Output

_	7	6	5	4	3	2	1	0
R W	PTEDS7	PTEDS6	PTEDS5	PTEDS4	PTEDS3	PTEDS2	PTEDS1	PTEDS0
Reset	0	0	0	0	0	0	0	0

Figure 6-33. Output Drive Strength Selection for Port E (PTEDS)

Table 6-26. PTEDS Register Field Descriptions

Field	Description
7:0 PTEDS[7:0]	 Output Drive Strength Selection for Port E Bits — Each of these control bits selects between low and high output drive for the associated PTE pin. 0 Low output drive enabled for port E bit n. 1 High output drive enabled for port E bit n.



Source		Description		Effect on CCR					ess de	ode	and	/cles ¹
Form	Operation	Description	v	н	I	N	z	с	Addr Moe	Opce	Oper	Bus C)
ROR opr8a RORA RORX ROR oprx8,X ROR ,X ROR oprx8,SP	Rotate Right through Carry	b7 b0	\$	_	_	\$	\$	\$	DIR INH INH IX1 IX SP1	36 46 56 66 76 9E66	dd ff ff	5 1 5 4 6
RSP	Reset Stack Pointer	SP ← 0xFF (High Byte Not Affected)	_	-	_	-	-	-	INH	9C		1
RTI	Return from Interrupt	$\begin{array}{l} SP \leftarrow (SP) + 0x0001; \ Pull \ (CCR) \\ SP \leftarrow (SP) + 0x0001; \ Pull \ (A) \\ SP \leftarrow (SP) + 0x0001; \ Pull \ (X) \\ SP \leftarrow (SP) + 0x0001; \ Pull \ (PCH) \\ SP \leftarrow (SP) + 0x0001; \ Pull \ (PCL) \end{array}$	\$	\$	\$	\$	\$	\$	INH	80		9
RTS	Return from Subroutine	$SP \leftarrow SP + 0x0001; Pull (PCH)$ $SP \leftarrow SP + 0x0001; Pull (PCL)$	-	-	-	-	-	-	INH	81		6
SBC #opr8i SBC opr8a SBC opr16a SBC oprx16,X SBC oprx8,X SBC ,X SBC oprx16,SP SBC oprx8,SP	Subtract with Carry	$A \leftarrow (A) - (M) - (C)$	\$	_	_	\$	\$	\$	IMM DIR EXT IX2 IX1 IX SP2 SP1	A2 B2 C2 D2 E2 F2 9ED2 9EE2	ii dd hh II ee ff ff ee ff	2 3 4 3 3 5 4
SEC	Set Carry Bit	C ← 1	-	-	—	-	-	1	INH	99		1
SEI	Set Interrupt Mask Bit	l ← 1	-	-	1	-	-	-	INH	9B		1
STA opr8a STA opr16a STA oprx16,X STA oprx8,X STA ,X STA oprx16,SP STA oprx8,SP	Store Accumulator in Memory	M ← (A)	0	_	_	\$	\$	_	DIR EXT IX2 IX1 IX SP2 SP1	87 C7 D7 E7 F7 9ED7 9EE7	dd hh ll ee ff ff ee ff ff	3 4 4 3 2 5 4
STHX opr8a STHX opr16a STHX oprx8,SP	Store H:X (Index Reg.)	(M:M + 0x0001) ← (H:X)	0	-	_	\$	\$	-	DIR EXT SP1	35 96 9EFF	dd hh ll ff	4 5 5
STOP	Enable Interrupts: Stop Processing Refer to MCU Documentation	I bit \leftarrow 0; Stop Processing	_	_	0	_	_	_	INH	8E		2+
STX opr8a STX opr16a STX oprx16,X STX oprx8,X STX ,X STX oprx16,SP STX oprx8,SP	Store X (Low 8 Bits of Index Register) in Memory	M ← (X)	0	_	_	\$	\$	_	DIR EXT IX2 IX1 IX SP2 SP1	BF CF DF EF 9EDF 9EEF	dd hh II ee ff ff ee ff ff	3443254
SUB #opr8i SUB opr8a SUB opr16a SUB oprx16,X SUB oprx8,X SUB ,X SUB oprx16,SP SUB oprx8,SP	Subtract	A ← (A) – (M)	\$	_	_	\$	\$	\$	IMM DIR EXT IX2 IX1 IX SP2 SP1	A0 B0 C0 D0 E0 F0 9ED0 9EE0	ii dd hh II ee ff ff ee ff ff	2 3 4 3 3 5 4
SWI	Software Interrupt	$\begin{array}{c} PC \leftarrow (PC) + 0x0001 \\ Push \ (PCL); \ SP \leftarrow (SP) - 0x0001 \\ Push \ (PCH); \ SP \leftarrow (SP) - 0x0001 \\ Push \ (A); \ SP \leftarrow (SP) - 0x0001 \\ Push \ (A); \ SP \leftarrow (SP) - 0x0001 \\ Push \ (CCR); \ SP \leftarrow (SP) - 0x0001 \\ I \leftarrow I; \\ PCH \leftarrow Interrupt \ Vector \ High \ Byte \\ PCL \leftarrow Interrupt \ Vector \ Low \ Byte \end{array}$	_	_	1	_	_	_	INH	83		11

Table 7-2. HC	S08 Instruction	Set Summary	(Sheet 6 of 7)	

MC9S08AW60 Data Sheet, Rev 2



Chapter 8 Internal Clock Generator (S08ICGV4)

The internal clock generation (ICG) module is used to generate the system clocks for the MC9S08AW60 Series MCU. The analog supply lines V_{DDA} and V_{SSA} are internally derived from the MCU's V_{DD} and V_{SS} pins. Electrical parametric data for the ICG may be found in Appendix A, "Electrical Characteristics and Timing Specifications."



Figure 8-1. System Clock Distribution Diagram

NOTE

Freescale Semiconductor recommends that FLASH location \$FFBE be reserved to store a nonvolatile version of ICGTRM. This will allow debugger and programmer vendors to perform a manual trim operation and store the resultant ICGTRM value for users to access at a later time.



8.1.3 Block Diagram

Figure 8-3 is a top-level diagram that shows the functional organization of the internal clock generation (ICG) module. This section includes a general description and a feature list.



Figure 8-3. ICG Block Diagram

8.2 External Signal Description

The oscillator pins are used to provide an external clock source for the MCU. The oscillator pins are gain controlled in low-power mode (default). Oscillator amplitudes in low-power mode are limited to approximately 1 V, peak-to-peak.

8.2.1 EXTAL — External Reference Clock / Oscillator Input

If upon the first write to ICGC1, either the FEE mode or FBE mode is selected, this pin functions as either the external clock input or the input of the oscillator circuit as determined by REFS. If upon the first write to ICGC1, either the FEI mode or SCM mode is selected, this pin is not used by the ICG.

8.2.2 XTAL — Oscillator Output

If upon the first write to ICGC1, either the FEE mode or FBE mode is selected, this pin functions as the output of the oscillator circuit. If upon the first write to ICGC1, either the FEI mode or SCM mode is



Chapter 9 Keyboard Interrupt (S08KBIV1)

9.3.1 KBI Block Diagram

Figure 9-2 shows the block diagram for a KBI module.



Figure 9-2. KBI Block Diagram

9.4 Register Definition

This section provides information about all registers and control bits associated with the KBI module.

Refer to the direct-page register summary in the Memory chapter of this data sheet for the absolute address assignments for all KBI registers. This section refers to registers and control bits only by their names. A Freescale-provided equate or header file is used to translate these names into the appropriate absolute addresses.



11.1.1 Features

Features of SCI module include:

- Full-duplex, standard non-return-to-zero (NRZ) format
- Double-buffered transmitter and receiver with separate enables
- Programmable baud rates (13-bit modulo divider)
- Interrupt-driven or polled operation:
 - Transmit data register empty and transmission complete
 - Receive data register full
 - Receive overrun, parity error, framing error, and noise error
 - Idle receiver detect
- Hardware parity generation and checking
- Programmable 8-bit or 9-bit character length
- Receiver wakeup by idle-line or address-mark
- Optional 13-bit break character
- Selectable transmitter output polarity

11.1.2 Modes of Operation

See Section 11.3, "Functional Description," for a detailed description of SCI operation in the different modes.

- 8- and 9-bit data modes
- Stop modes SCI is halted during all stop modes
- Loop mode
- Single-wire mode

11.1.3 Block Diagram

Figure 11-2 shows the transmitter portion of the SCI.



Chapter 11 Serial Communications Interface (S08SCIV2)

11.2.3 SCI Control Register 2 (SCIxC2)

This register can be read or written at any time.



Figure 11-7. SCI Control Register 2 (SCIxC2)

Table 11-4. SCIxC2 Register Field Descriptions

Field	Description
7 TIE	Transmit Interrupt Enable (for TDRE)0Hardware interrupts from TDRE disabled (use polling).1Hardware interrupt requested when TDRE flag is 1.
6 TCIE	Transmission Complete Interrupt Enable (for TC)0Hardware interrupts from TC disabled (use polling).1Hardware interrupt requested when TC flag is 1.
5 RIE	Receiver Interrupt Enable (for RDRF)0Hardware interrupts from RDRF disabled (use polling).1Hardware interrupt requested when RDRF flag is 1.
4 ILIE	Idle Line Interrupt Enable (for IDLE)00111Hardware interrupt requested when IDLE flag is 1.
3 TE	Transmitter Enable0Transmitter off.1Transmitter on.TE must be 1 in order to use the SCI transmitter. Normally, when TE = 1, the SCI forces the TxD pin to act as an output for the SCI system. If LOOPS = 1 and RSRC = 0, the TxD pin reverts to being a port B general-purpose I/O pin even if TE = 1.When the SCI is configured for single-wire operation (LOOPS = RSRC = 1), TXDIR controls the direction of traffic on the single SCI communication line (TxD pin).TE also can be used to queue an idle character by writing TE = 0 then TE = 1 while a transmission is in progress.Refer to Section 11.3.2.1, "Send Break and Queued Idle" for more details.When TE is written to 0, the transmitter keeps control of the port TxD pin until any data, queued idle, or queued break character finishes transmitting before allowing the pin to revert to a general-purpose I/O pin.
2 RE	Receiver Enable — When the SCI receiver is off, the RxD pin reverts to being a general-purpose port I/O pin. 0 Receiver off. 1 Receiver on.



Chapter 11 Serial Communications Interface (S08SCIV2)

character(s) of each message, and as soon as they determine the message is intended for a different receiver, they write logic 1 to the receiver wake up (RWU) control bit in SCIxC2. When RWU = 1, it inhibits setting of the status flags associated with the receiver, thus eliminating the software overhead for handling the unimportant message characters. At the end of a message, or at the beginning of the next message, all receivers automatically force RWU to 0 so all receivers wake up in time to look at the first character(s) of the next message.

11.3.3.2.1 Idle-Line Wakeup

When WAKE = 0, the receiver is configured for idle-line wakeup. In this mode, RWU is cleared automatically when the receiver detects a full character time of the idle-line level. The M control bit selects 8-bit or 9-bit data mode that determines how many bit times of idle are needed to constitute a full character time (10 or 11 bit times because of the start and stop bits).

When the RWU bit is set, the idle character that wakes a receiver does not set the receiver idle bit, IDLE, or the receive data register full flag, RDRF. It therefore will not generate an interrupt when this idle character occurs. The receiver will wake up and wait for the next data transmission which will set RDRF and generate an interrupt if enabled.

The idle-line type (ILT) control bit selects one of two ways to detect an idle line. When ILT = 0, the idle bit counter starts after the start bit so the stop bit and any logic 1s at the end of a character count toward the full character time of idle. When ILT = 1, the idle bit counter does not start until after a stop bit time, so the idle detection is not affected by the data in the last character of the previous message.

11.3.3.2.2 Address-Mark Wakeup

When WAKE = 1, the receiver is configured for address-mark wakeup. In this mode, RWU is cleared automatically when the receiver detects a logic 1 in the most significant bit of a received character (eighth bit in M = 0 mode and ninth bit in M = 1 mode).

Address-mark wakeup allows messages to contain idle characters but requires that the MSB be reserved for use in address frames. The logic 1 MSB of an address frame clears the receivers RWU bit before the stop bit is received and sets the RDRF flag.

11.3.4 Interrupts and Status Flags

The SCI system has three separate interrupt vectors to reduce the amount of software needed to isolate the cause of the interrupt. One interrupt vector is associated with the transmitter for TDRE and TC events. Another interrupt vector is associated with the receiver for RDRF and IDLE events, and a third vector is used for OR, NF, FE, and PF error conditions. Each of these eight interrupt sources can be separately masked by local interrupt enable masks. The flags can still be polled by software when the local masks are cleared to disable generation of hardware interrupt requests.

The SCI transmitter has two status flags that optionally can generate hardware interrupt requests. Transmit data register empty (TDRE) indicates when there is room in the transmit data buffer to write another transmit character to SCIxD. If the transmit interrupt enable (TIE) bit is set, a hardware interrupt will be requested whenever TDRE = 1. Transmit complete (TC) indicates that the transmitter is finished transmitting all data, preamble, and break characters and is idle with TxD high. This flag is often used in



Chapter 12 Serial Peripheral Interface (S08SPIV3)

The most common uses of the SPI system include connecting simple shift registers for adding input or output ports or connecting small peripheral devices such as serial A/D or D/A converters. Although Figure 12-2 shows a system where data is exchanged between two MCUs, many practical systems involve simpler connections where data is unidirectionally transferred from the master MCU to a slave or from a slave to the master MCU.

12.0.2.2 SPI Module Block Diagram

Figure 12-3 is a block diagram of the SPI module. The central element of the SPI is the SPI shift register. Data is written to the double-buffered transmitter (write to SPI1D) and gets transferred to the SPI shift register at the start of a data transfer. After shifting in a byte of data, the data is transferred into the double-buffered receiver where it can be read (read from SPI1D). Pin multiplexing logic controls connections between MCU pins and the SPI module.

When the SPI is configured as a master, the clock output is routed to the SPSCK pin, the shifter output is routed to MOSI, and the shifter input is routed from the MISO pin.

When the SPI is configured as a slave, the SPSCK pin is routed to the clock input of the SPI, the shifter output is routed to MISO, and the shifter input is routed from the MOSI pin.

In the external SPI system, simply connect all SPSCK pins to each other, all MISO pins together, and all MOSI pins together. Peripheral devices often use slightly different names for these pins.

Chapter 12 Serial Peripheral Interface (S08SPIV3)

SPPR2:SPPR1:SPPR0	Prescaler Divisor
0:0:0	1
0:0:1	2
0:1:0	3
0:1:1	4
1:0:0	5
1:0:1	6
1:1:0	7
1:1:1	8

Table 12-5. SPI Baud Rate Prescaler Divisor

Table 12-6. SPI Baud Rate Divisor

SPR2:SPR1:SPR0	Rate Divisor
0:0:0	2
0:0:1	4
0:1:0	8
0:1:1	16
1:0:0	32
1:0:1	64
1:1:0	128
1:1:1	256

12.3.4 SPI Status Register (SPI1S)

This register has three read-only status bits. Bits 6, 3, 2, 1, and 0 are not implemented and always read 0. Writes have no meaning or effect.



Figure 12-8. SPI Status Register (SPI1S)

Chapter 12 Serial Peripheral Interface (S08SPIV3)

in LSBFE. Both variations of SPSCK polarity are shown, but only one of these waveforms applies for a specific transfer, depending on the value in CPOL. The SAMPLE IN waveform applies to the MOSI input of a slave or the MISO input of a master. The MOSI waveform applies to the MOSI output pin from a master and the MISO waveform applies to the MISO output from a slave. The \overline{SS} OUT waveform applies to the slave select output from a master (provided MODFEN and SSOE = 1). The master \overline{SS} output goes to active low at the start of the first bit time of the transfer and goes back high one-half SPSCK cycle after the end of the eighth bit time of the transfer. The \overline{SS} IN waveform applies to the slave select input of a slave.





When CPHA = 0, the slave begins to drive its MISO output with the first data bit value (MSB or LSB depending on LSBFE) when \overline{SS} goes to active low. The first SPSCK edge causes both the master and the slave to sample the data bit values on their MISO and MOSI inputs, respectively. At the second SPSCK edge, the SPI shifter shifts one bit position which shifts in the bit value that was just sampled and shifts the second data bit value out the other end of the shifter to the MOSI and MISO outputs of the master and slave, respectively. When CPHA = 0, the slave's \overline{SS} input must go to its inactive high level between transfers.



12.4.2 SPI Interrupts

There are three flag bits, two interrupt mask bits, and one interrupt vector associated with the SPI system. The SPI interrupt enable mask (SPIE) enables interrupts from the SPI receiver full flag (SPRF) and mode fault flag (MODF). The SPI transmit interrupt enable mask (SPTIE) enables interrupts from the SPI transmit buffer empty flag (SPTEF). When one of the flag bits is set, and the associated interrupt mask bit is set, a hardware interrupt request is sent to the CPU. If the interrupt mask bits are cleared, software can poll the associated flag bits instead of using interrupts. The SPI interrupt service routine (ISR) should check the flag bits to determine what event caused the interrupt. The service routine should also clear the flag bit(s) before returning from the ISR (usually near the beginning of the ISR).

12.4.3 Mode Fault Detection

A mode fault occurs and the mode fault flag (MODF) becomes set when a master SPI device detects an error on the \overline{SS} pin (provided the \overline{SS} pin is configured as the mode fault input signal). The \overline{SS} pin is configured to be the mode fault input signal when MSTR = 1, mode fault enable is set (MODFEN = 1), and slave select output enable is clear (SSOE = 0).

The mode fault detection feature can be used in a system where more than one SPI device might become a master at the same time. The error is detected when a master's \overline{SS} pin is low, indicating that some other SPI device is trying to address this master as if it were a slave. This could indicate a harmful output driver conflict, so the mode fault logic is designed to disable all SPI output drivers when such an error is detected.

When a mode fault is detected, MODF is set and MSTR is cleared to change the SPI configuration back to slave mode. The output drivers on the SPSCK, MOSI, and MISO (if not bidirectional mode) are disabled.

MODF is cleared by reading it while it is set, then writing to the SPI control register 1 (SPI1C1). User software should verify the error condition has been corrected before changing the SPI back to master mode.



Chapter 14 Analog-to-Digital Converter (S08ADC10V1)

ADCH	Input Select
01000	AD8
01001	AD9
01010	AD10
01011	AD11
01100	AD12
01101	AD13
01110	AD14
01111	AD15

ADCH	Input Select
11000	AD24
11001	AD25
11010	AD26
11011	AD27
11100	Reserved
11101	V _{REFH}
11110	V _{REFL}
11111	Module disabled

Figure 14-4. Input Channel Select (continued)

14.4.2 Status and Control Register 2 (ADC1SC2)

The ADC1SC2 register is used to control the compare function, conversion trigger and conversion active of the ADC module.



¹ Bits 1 and 0 are reserved bits that must always be written to 0.

Figure 14-5. Status and Control Register 2 (ADC1SC2)

Table 14-4. ADC1SC2 Register Field Descriptions

Field	Description
7 ADACT	 Conversion Active — ADACT indicates that a conversion is in progress. ADACT is set when a conversion is initiated and cleared when a conversion is completed or aborted. 0 Conversion not in progress 1 Conversion in progress
6 ADTRG	 Conversion Trigger Select — ADTRG is used to select the type of trigger to be used for initiating a conversion. Two types of trigger are selectable: software trigger and hardware trigger. When software trigger is selected, a conversion is initiated following a write to ADC1SC1. When hardware trigger is selected, a conversion is initiated following the assertion of the ADHWT input. O Software trigger selected Hardware trigger selected



Chapter 14 Analog-to-Digital Converter (S08ADC10V1)



How to Reach Us:

USA/Europe/Locations not listed:

Freescale Semiconductor Literature Distribution P.O. Box 5405, Denver, Colorado 80217 1-800-521-6274 or 480-768-2130

Japan:

Freescale Semiconductor Japan Ltd. SPS, Technical Information Center 3-20-1, Minami-Azabu Minato-ku Tokyo 106-8573, Japan 81-3-3440-3569

Asia/Pacific:

Freescale Semiconductor H.K. Ltd. 2 Dai King Street Tai Po Industrial Estate Tai Po, N.T. Hong Kong 852-26668334

Learn More: For more information about Freescale Semiconductor products, please visit http://www.freescale.com

MC9S08AW60, Rev 2 12/2006

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters which may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale[™] and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners. © Freescale Semiconductor, Inc. 2005.

